STD123S

DATA SHEET

/ Descriptions

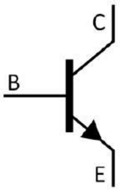
SOT-23 NPN

/ Features

,

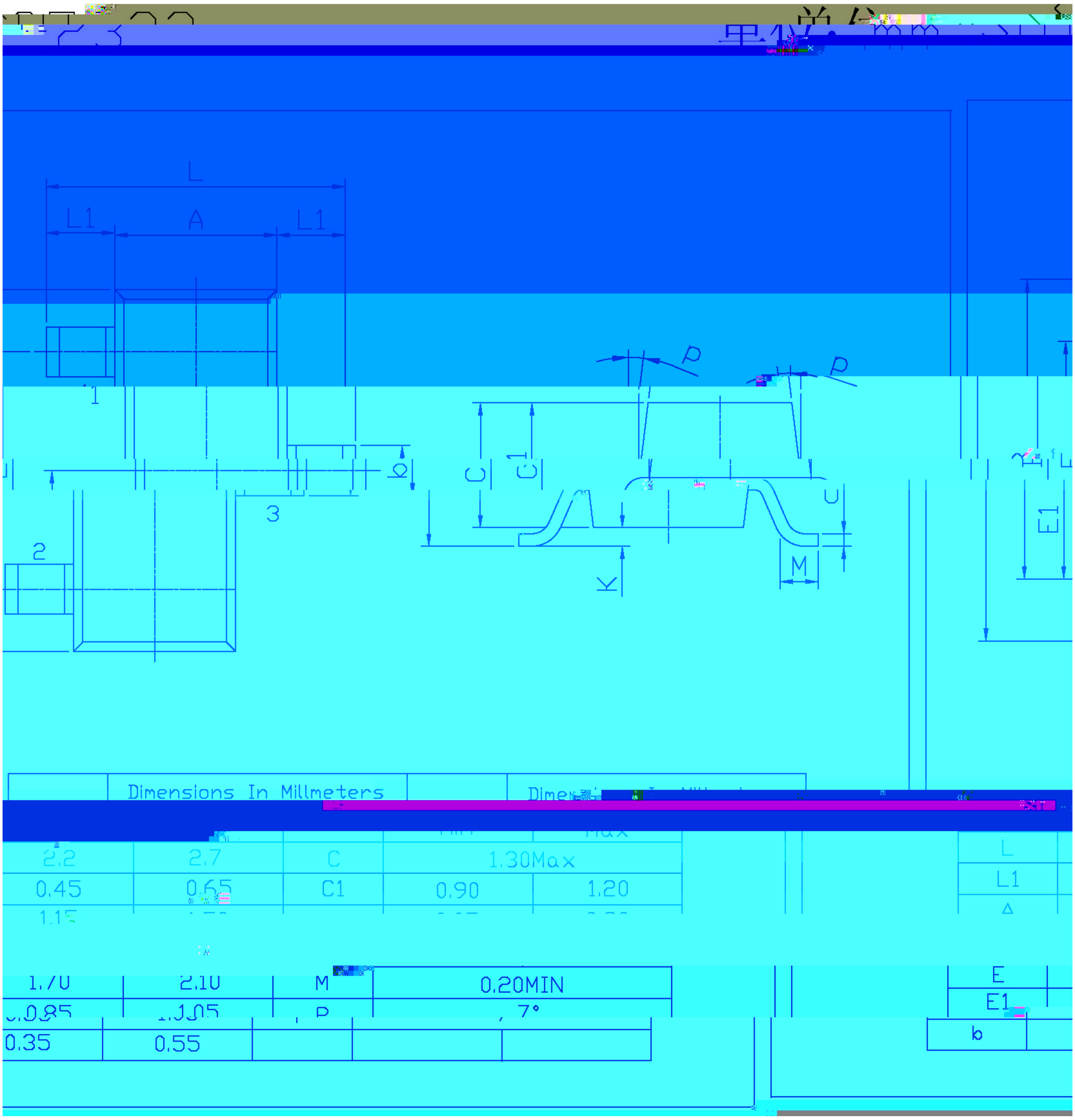
/ Applications

/ Equivalent Circuit

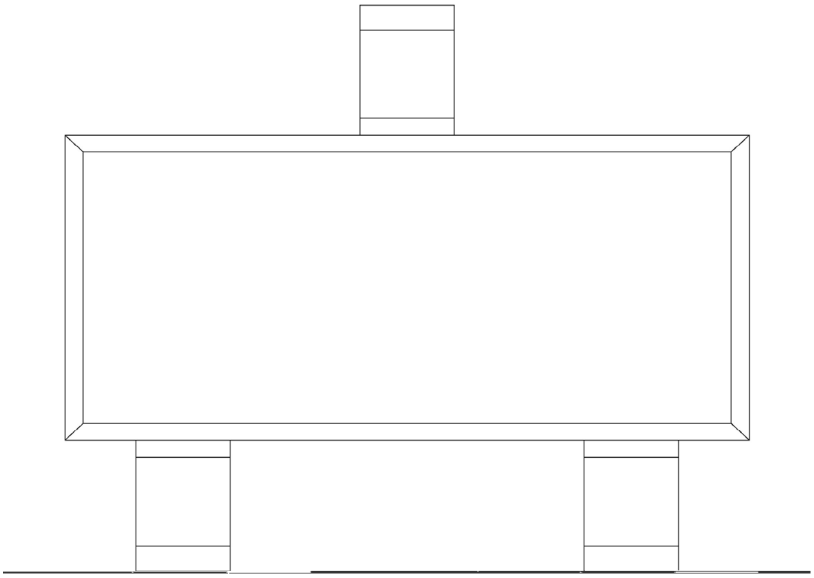


/ h_{FE} Classifications & Marking

/ Package Dimensions



/ Marking Instructions



H

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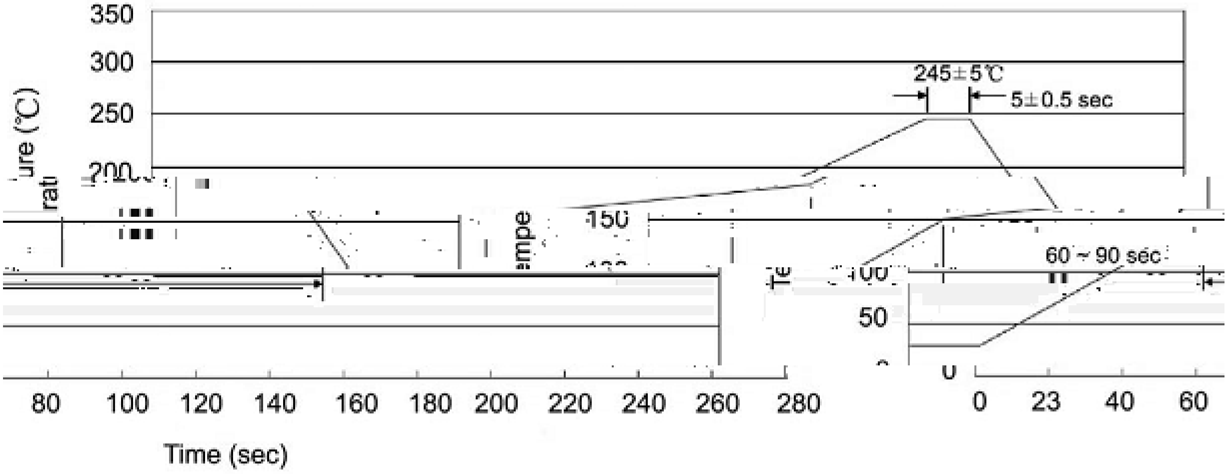
( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



± ± ± ±

/ Resistance to Soldering Heat Test Conditions

± ±

/ Packaging SPEC.

封装形式	包装数量					包装尺寸 :		
	只 卷盘	卷盘 盒	只 盒	盒 箱	只 箱		盒	箱

/ Notices